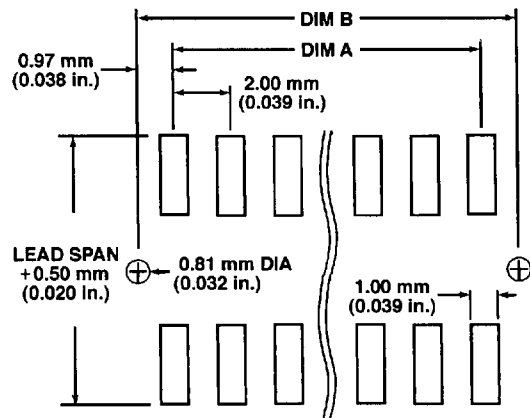
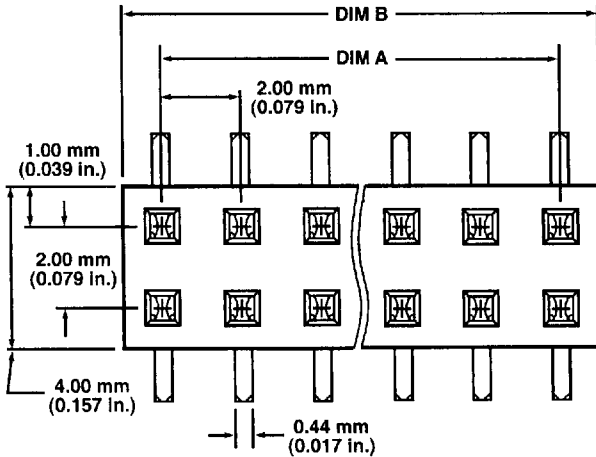
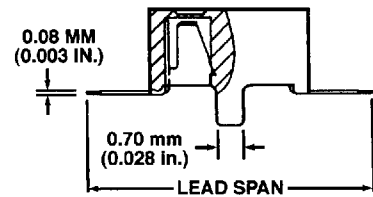
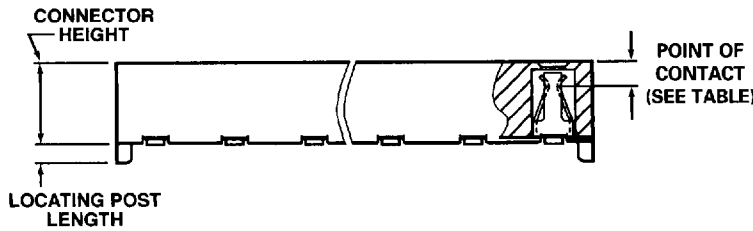


### Description

### Vertical, Top-Entry, Surface Mount Receptacle



RECOMMENDED PAD LAYOUT



NOTE: PRODUCT IS SHOWN WITH OPTIONAL LOCATING POSTS.

### Ordering Data

### Vertical, Top-Entry, Surface Mount Receptacle

Base number specifies housing configuration, and connector height.

Dash number specifies contact finish (X) and number of positions (YY).

□ □ □ □ □ - X Y Y

Add suffix "TR" to dash number for tape-and-reel packaging.

Base Number	Connector Height		Lead Span		Locating Post		Point of Contact	
	mm	in.	mm	in.	mm	in.	mm	in.
92844	2.10	0.083	6.78	0.267	N/A	N/A	0.62	0.025
92429	2.10	0.083	6.78	0.267	0.76	0.030	0.62	0.025
92431	2.10	0.083	6.78	0.267	0.30	0.012	0.62	0.025
91592	2.30	0.091	6.00	0.236	N/A	N/A	0.81	0.032
92082	2.30	0.091	6.78	0.267	0.30	0.012	0.81	0.032
92090	2.30	0.091	6.78	0.267	0.76	0.030	0.81	0.032
91802	3.00	0.118	6.00	0.236	N/A	N/A	0.62	0.025
92911	3.00	0.118	6.00	0.236	0.46	0.018	0.62	0.025
91812	4.00	0.157	6.00	0.236	N/A	N/A	0.62	0.025
92086	4.00	0.157	6.00	0.236	0.46	0.018	0.62	0.025

X: Contact Finish

1 = 0.76 μm (30 μin.) gold

3 = 0.38 μm (15 μin.) gold

No. of Positions	Dash Number	Dimension A		Dimension B		No. of Positions	Dash Number	Dimension A		Dimension B	
		mm	in.	mm	in.			mm	in.	mm	in.
2 x 2	X04	2.00	0.079	3.92	0.154	2 x 9	X18	16.00	0.630	17.92	0.706
2 x 3	X06	4.00	0.157	5.92	0.233	2 x 10	X20	18.00	0.709	19.92	0.784
2 x 4	X08	6.00	0.236	7.92	0.312	2 x 11	X22	20.00	0.787	21.92	0.863
2 x 5	X10	8.00	0.315	9.92	0.391	2 x 12	X24	22.00	0.866	23.92	0.942
2 x 6	X12	10.00	0.394	11.92	0.469	2 x 13	X26	24.00	0.945	25.92	1.020
2 x 7	X14	12.00	0.472	13.92	0.548	2 x 14	X28	26.00	1.024	27.92	1.099
2 x 8	X16	14.00	0.551	15.92	0.627	2 x 15	X30	28.00	1.102	29.92	1.178

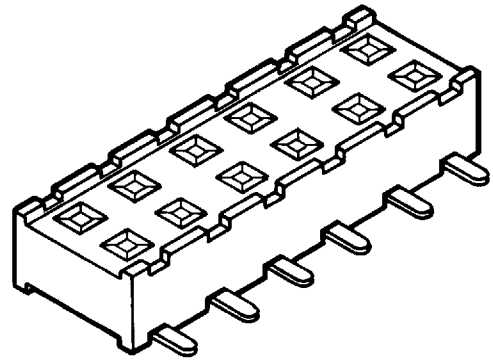
Ordering data shown is for our standard product offering. For non-standard or custom products, contact your authorized Berg Electronics representative.

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# PCB Mounted Receptacles

2.00 x 2.00 mm (0.079 x 0.079 in.) Centerlines

## Minitek™ Vertical Receptacles Top-Entry, Surface-Mount



### Features

- 2 x 2 through 2 x 15 positions.
- Early-entry dual-beam contacts provide long wiping action for reliable electrical contact
- Closed front and beveled lead-in ramps at receptacle openings protect against contact damage
- Low profile housing stands just 2.10 mm (0.083 in.) tall permitting close board-to-board spacing.
- Taller 2.30 mm (0.091 in.), 3.00 mm (0.118 in.) or 4.00 mm (0.157 in.) body heights can be used to provide additional clearance between boards for larger components.
- Duplex-plated contact with gold finish in contact areas and tin-lead in solder areas
- Can be stacked end-to-end on 2.00 mm (0.079 in.) pitch
- High temperature plastic withstands reflow soldering temperatures.

- Packaged in tubes for protection
- 0.10 mm (0.004 in.) coplanarity

### Options

- Tape-and-reel packaging
- Polarization through molded-in position.
- Locating posts.

### Mating Data


Mates with 0.50 mm (0.020 in.) square pin 2.00 mm (0.079 in.) long.


Berg Electronics Products	Page
▪ Minitek™ unshrouded headers . . . . .	9-8 to 9-21
▪ Minitek™ straddle-mount headers . . . . .	9-22
▪ Minitek™ pins (in pre-loaded pin carrier) . . . . .	9-18

### Specifications

- JIS-5020
- MIL-STD-202

### Approvals and Certifications

 File no. E66906

 File no. LR46923

### Technical Data

#### Materials

- High-temperature housing . . . . . Glass-filled PCT (UL 94 V-0)
  - ▶ Color . . . . . Black
  - ▶ Applicable soldering processes . . . . . IR, vapor-phase
- Receptacle . . . . . Beryllium copper

#### Mechanical Performance

- Insertion force . . . . . 1.95 N (200 gf) max per contact
- Withdrawal force . . . . . 0.20 N (20 gf) min per contact
- Terminal retention force . . . . . 2.20 N (227 gf) min
- Durability (mating cycles) . . . . . 25

#### Electrical Performance

- Insulation resistance . . . . . 1000 MΩ min
- Withstanding voltage . . . . . 500 V rms
- Current rating . . . . . 1 amp continuous
- Contact resistance . . . . . 20 mΩ max

#### Plating

- Underplate . . . . . 1.27 μm (50 μin.) min nickel
- Finish
  - ▶ Contact area . . . . . 0.38 μm (15 μin.) min gold or 0.76 μm (30 μin.) min gold
  - ▶ Solder area . . . . . 2.54 μm (100 μin.) min tin-lead

#### Operating Environment

- Temperature range . . . . . -55°C to +105°C

#### Packaging

- Tubes
- Tape-and-reel (optional)

### Customer Support Materials

Description	Order No.	Description	Order No.
Customer Product Drawings . . . . .	By Part No.	Product Bulletin . . . . .	950522-001
Product Samples . . . . .	By Part No.	Product Specifications . . . . .	GES-12-008

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